



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C681FB8NNNC
- Description : CAP, 680pF, 50V, ±1%, C0G, 0603

A. Samsung Part Number

			<u>CL</u>	<u>10</u>	<u>C</u>	<u>681</u>	E	<u>B</u>	<u>8</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>c</u>			
			1	2	3	4	(5)	6	1	8	9	10	1			
1	Series	Samsung Multi-layer Ceramic Capacitor														
2	Size	0603	(inch c	ode)		L:	1.6	± 0.1		mm		W:	0.8	± 0.1	mm	
3	Dielectric	C0G					8	Inne	r ele	ctroc	le		Ni			
4	Capacitance	680	рF					Tern	ninat	tion			Cu			
5	Capacitance	±1	%					Plati	ng				Sn 10	00%	(Pb Free)	
	tolerance						9	Prod	luct				Norm	al		
6	Rated Voltage	50	V				10	Spec	cial				Rese	rved for	r future use	
\bigcirc	Thickness	0.8	± 0.1	mm			1	Pack	agir	ng			Card	board T	ype, 7" reel	

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms						
Q	1000 min							
Insulation	10,000Mohm or 500Mohm µF	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance No abnormal exterior appearance		Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	COG							
Characterisitcs	(From -55 $^\circ$ C to 125 $^\circ$ C, Capacitance change shoud be within ±30PPM/ $^\circ$ C)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10H₂ to 55H₂ (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	r 40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 200 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 350 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperatur \rightarrow 25 °C					
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.